## **ESD Protection Diode**

### Ultra Small SOT-1123 Package

The ESD11A Series is designed to protect voltage sensitive components from damage due to ESD. These parts provide excellent ESD clamping capability and fast response time to enhance the immunity of the end application from system level ESD stress such as IEC61000–4–2. Two uni–directional surge protection diodes are housed in the ultra small SOT–1123 package, making these parts ideal for ESD protection on designs where board space is at a premium, such as cell phones, MP3 players and many other portable handheld electronic devices.



- Low Clamping Voltage
- Small Body Outline Dimensions:

0.039" x 0.024" (1.0 mm x 0.6 mm)

• Low Body Height: 0.016" (0.4 mm)

• Stand-off Voltage: 3.3 V - 5 V

• Low Leakage

• Response Time is Typically < 1 ns

• IEC61000-4-2 Level 4 ESD Protection

• AEC-Q101 Qualified and PPAP Capable

• These are Pb-Free Devices

#### **Mechanical Characteristics:**

CASE: Void-free, transfer-molded, thermosetting plastic

Epoxy Meets UL 94 V-0

**LEAD FINISH:** 100% Matte Sn (Tin)

**MOUNTING POSITION:** Any

QUALIFIED MAX REFLOW TEMPERATURE: 260°C

Device Meets MSL 1 Requirements

**Table 1. MAXIMUM RATINGS** 

Rating	Symbol	Value	Unit
IEC 61000-4-2 (ESD) Contact		±15	kV
Total Power Dissipation on FR-5 Board (Note 1) @ T <sub>A</sub> = 25°C	P <sub>D</sub>	150	mW
Storage Temperature Range	T <sub>stg</sub>	-55 to +150	°C
Junction Temperature Range	$T_J$	-55 to +125	°C
Lead Solder Temperature – Maximum (10 Second Duration)	TL	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1.  $FR-5 = 1.0 \times 0.75 \times 0.62$  in.

See Application Note AND8308/D for further description of ESD maximum ratings.

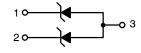


#### ON Semiconductor®

#### www.onsemi.com

PIN 1. CATHODE 2. CATHODE

3. ANODE





SOT-1123 CASE 524AA

#### MARKING DIAGRAM



X = Specific Device Code

M = Date Code

#### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
ESD11AxxDT5G	SOT-1123 (Pb-Free)	8000/Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

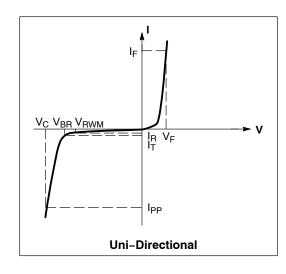
#### **DEVICE MARKING INFORMATION**

See specific marking information in the device marking column of the table on page 2 of this data sheet.

#### **Table 2. ELECTRICAL CHARACTERISTICS**

(T<sub>A</sub> = 25°C unless otherwise noted)

Symbol	Parameter			
I <sub>PP</sub>	Maximum Reverse Peak Pulse Current			
V <sub>C</sub>	Clamping Voltage @ I <sub>PP</sub>			
$V_{RWM}$	Working Peak Reverse Voltage			
I <sub>R</sub>	Maximum Reverse Leakage Current @ V <sub>RWM</sub>			
V <sub>BR</sub>	Breakdown Voltage @ I <sub>T</sub>			
Ι <sub>Τ</sub>	Test Current			
lF	Forward Current			
V <sub>F</sub>	Forward Voltage @ I <sub>F</sub>			
P <sub>pk</sub>	Peak Power Dissipation			
С	Capacitance @V <sub>R</sub> = 0 and f = 1 MHz			



 $\textbf{Table 3. ELECTRICAL CHARACTERISTICS} \ (T_{A} = 25^{\circ}\text{C unless otherwise noted}, \ V_{F} = 0.9 \ \text{V Max.} \ \textcircled{0} \ I_{F} = 10 \ \text{mA for all types})$ 

	Device	V <sub>RWM</sub> (V)	I <sub>R</sub> (μΑ) @ V <sub>RWM</sub>	V <sub>BR</sub> (V) @ I <sub>T</sub> (Note 2)	Ι <sub>Τ</sub>	C (pF), uni-directional (Note 3)		V <sub>C</sub> (V) @ I <sub>PP</sub> = 1 A (Note 5)	V <sub>C</sub> (V) IEC61000-4-2 (Note 6)
Device	Marking	Max	Max	Min	mA	Тур	Max	Max	Тур
ESD11A3.3DT5G	2*	3.3	1.0	5.2	1.0	25	35	7.8	Figures 1 thru 4
ESD11A5.0DT5G	3*	5.0	0.1	6.2	1.0	20	30	9.5	Figures 1 thru 4

<sup>\*</sup>Rotated 90° clockwise.

- V<sub>BR</sub> is measured with a pulse test current I<sub>T</sub> at an ambient temperature of 25°C.
   Uni-directional capacitance at f = 1 MHz, V<sub>R</sub> = 0 V, T<sub>A</sub> = 25°C (pin1 to pin 3; pin 2 to pin 3).
   Bi-directional capacitance at f = 1 MHz, V<sub>R</sub> = 0 V, T<sub>A</sub> = 25°C (pin1 to pin 2).
   Surge current waveform per Figure 7.
   Typical waveform. For test procedure see Figures 5 and 6 and Application Note AND8307/D.

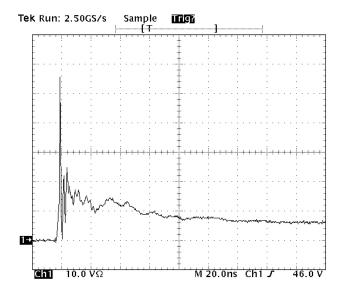


Figure 1. ESD11A3.3D Clamping Voltage Screenshot Positive 8 kV contact per IEC 61000-4-2

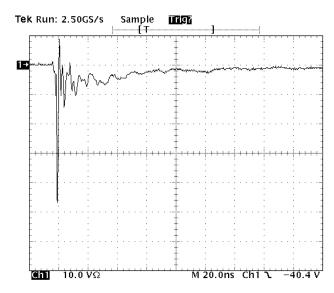


Figure 2. ESD11A3.3D Clamping Voltage Screenshot Negative 8 kV contact per IEC 61000-4-2

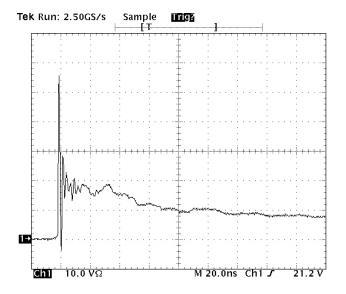


Figure 3. ESD11A5.0D Clamping Voltage Screenshot Positive 8 kV contact per IEC 61000-4-2

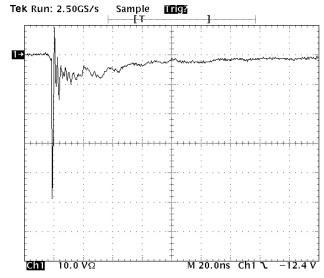


Figure 4. ESD11A5.0D Clamping Voltage Screenshot Negative 8 kV contact per IEC 61000-4-2

#### IEC 61000-4-2 Spec.

Level	Test Voltage (kV)	First Peak Current (A)	Current at 30 ns (A)	Current at 60 ns (A)
1	2	7.5	4	2
2	4	15	8	4
3	6	22.5	12	6
4	8	30	16	8

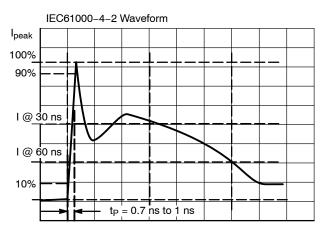


Figure 5. IEC61000-4-2 Spec

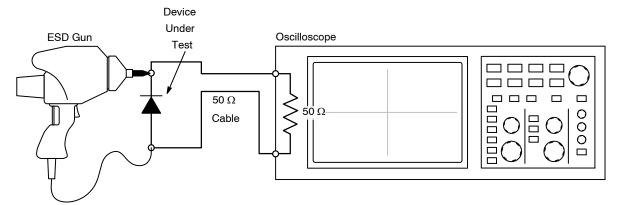


Figure 6. Diagram of ESD Test Setup

The following is taken from Application Note AND8308/D – Interpretation of Datasheet Parameters for ESD Devices.

#### **ESD Voltage Clamping**

For sensitive circuit elements it is important to limit the voltage that an IC will be exposed to during an ESD event to as low a voltage as possible. The ESD clamping voltage is the voltage drop across the ESD protection diode during an ESD event per the IEC61000-4-2 waveform. Since the IEC61000-4-2 was written as a pass/fail spec for larger

systems such as cell phones or laptop computers it is not clearly defined in the spec how to specify a clamping voltage at the device level. ON Semiconductor has developed a way to examine the entire voltage waveform across the ESD protection diode over the time domain of an ESD pulse in the form of an oscilloscope screenshot, which can be found on the datasheets for all ESD protection diodes. For more information on how ON Semiconductor creates these screenshots and how to interpret them please refer to AND8307/D.

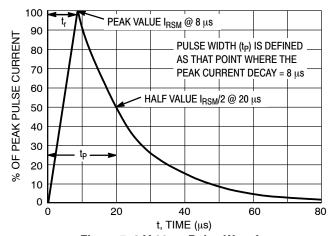


Figure 7. 8 X 20 μs Pulse Waveform



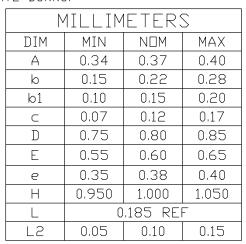


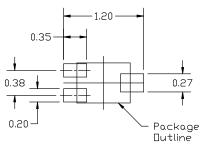
#### SOT-1123 0.80x0.60x0.37, 0.35P CASE 524AA ISSUE D

**DATE 18 JAN 2024** 

#### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
- 2. CONTROLLING DIMENSION: MILLIMETERS.
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH.
  MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS
  OF BASE MATERIAL.
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

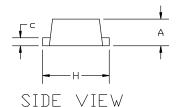


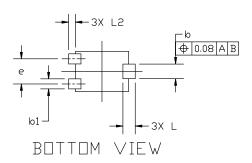


# RECOMMENDED MOUNTING FOOTPRINT

\*For additional information on our Pb-Free strategy and soldering details, please download th e □N Semiconductor Soldering and Mounting Techniques Reference manual, S□LDERRM/D.

# TOP VIEW





# GENERIC MARKING DIAGRAM\*



X = Specific Device CodeM = Date Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

STYLE 1:
PIN 1. BASE
<ol><li>EMITTER</li></ol>
3 COLLECTOR

STYLE 2: PIN 1. ANODE 2. N/C 3. CATHODE

STYLE 3: PIN 1. ANODE 2. ANODE 3. CATHODE

STYLE 4: PIN 1. CATHODE 2. CATHODE 3. ANODE STYLE 5: PIN 1. GATE 2. SOURCE

DOCUMENT NUMBER:	98AON23134D	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	SOT-1123 0.80x0.60x0.37, 0.35P		PAGE 1 OF 1	

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

onsemi, Onsemi, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at <a href="www.onsemi.com/site/pdf/Patent-Marking.pdf">www.onsemi.com/site/pdf/Patent-Marking.pdf</a>. Onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA class 3 medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase

#### ADDITIONAL INFORMATION

**TECHNICAL PUBLICATIONS:** 

 $\textbf{Technical Library:} \ \underline{www.onsemi.com/design/resources/technical-documentation}$ 

onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at

www.onsemi.com/support/sales